

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Masatake NAKANO, Kiyoshi MITANI
and Shinichi TOMIZAWA

Application No.: US National Stage of PCT/JP00/06795

Filed: June 7, 2001

Docket No.: 109716

For: METHOD FOR PRODUCING BONDING WAFER AND BONDING WAFER

INFORMATION DISCLOSURE STATEMENT

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

Pursuant to 37 CFR §1.56, the attention of the Patent and Trademark Office is hereby directed to the references listed on the attached PTO-1449. Unless otherwise indicated herein, one copy of each reference is attached. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the references be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

- ☐ 1. This Information Disclosure Statement is being filed (a) within three months of the U.S. filing date of this non-CPA application, OR (b) before the mailing date of a first Office Action on the merits in the present application. No certification or fee is required.
- ☐ 2. Relevance of the non-English language references 1, 3 and 4 is discussed in the present specification.
- ☐ 3. References 2, and 5-8 were cited in a counterpart foreign application. An English language version of the foreign search report is attached for the Examiner's information.
- ☐ 4. English-language Abstracts of the non-English language references 1-7 are attached hereto.

Respectfully submitted,



William P. Berridge
Registration No. 30,024

Thomas J. Pardini
Registration No. 30,411

WPB:TJP/zmc
Date: June 7, 2001

OLIFF & BERRIDGE, PLC
P.O. Box 19928
Alexandria, Virginia 22320
Telephone: (703) 836-6400

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